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**PATENT NUMBER and
ISSUE DATE**

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10076244	02/13/2002	438	108	2813	Nema Berezny

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Nema has
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****CONTINUING DATA VERIFIED:**

This application is a CIP of 09/612,576 07/07/2000 ABN

**** FOREIGN APPLICATIONS VERIFIED:**

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed		<input type="checkbox"/> yes <input type="checkbox"/> no
35 USC 119 conditions met		<input type="checkbox"/> yes <input type="checkbox"/> no
Verifier and Acknowledged Examiners's initials		
		ATTORNEY DOCKET NO
		CS99-343C
TITLE : Method of copper/copper surface bonding using a conducting polymer for application in IC chip bonding		
U.S.DEP.T. OF COMM./PAT. & TM-PTO-436L(Rev. 12-94)		

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G
ISSUE FEE			DRAWING	
Amount Due	Date Paid		Sheets Drwg.	Figs.Drwg.
 		Primary Examiner	 	
 		PREPARED FOR ISSUE	 Application Examiner	
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